Field-induced charged-device model test method for electrostatic discharge withstand thresholds of microelectronic components
JEDEC STANDARD

Test Method C101

Field-Induced Charged-Device Model Test Method for Electrostatic Discharge Withstand Thresholds of Microelectronic Components

JESD22-C101

MAY 1995

ELECTRONIC INDUSTRIES ASSOCIATION
ENGINEERING DEPARTMENT
INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD
FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS
OF MICROELECTRONIC COMPONENTS

FOREWORD

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IEC-PAS 62162 was submitted by JEDEC and has been processed by IEC technical committee 47: Semiconductor
devices.

The text of this PAS is based on the
following document:

This PAS was approved for
publication by the P-members of the
committee concerned as indicated in
the following document:

<table>
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<th>Draft PAS</th>
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FIELD-INDUCED CHARGED-DEVICE MODEL TEST METHOD FOR ELECTROSTATIC DISCHARGE WITHSTAND THRESHOLDS OF MICROELECTRONIC COMPONENTS

1. PURPOSE
This standard describes a uniform method for establishing charged-device model (CDM) electrostatic discharge (ESD) withstand thresholds.

2. SCOPE
All packaged semiconductor components, thin film circuits, surface acoustic wave (SAW) components, opto-electronic components, hybrid integrated circuits (HICS), and multi-chip modules (MCMs) containing any of these components are to be evaluated according to this standard. The test methods described in this standard may also be used to evaluate components that are shipped as wafers or bare chips. To perform the tests, the components must be assembled into a package similar to that expected in the final application. The package used shall be recorded.

3. REFERENCE DOCUMENT
JEDEC Standard No. 42, “Requirements for Handling Electrostatic-Discharge-Sensitive (ESDS) Devices.”